

Title (en)
HIGH-FREQUENCY HEATING DEVICE

Title (de)
HOCHFREQUENZERWÄRMUNGSVORRICHTUNG

Title (fr)
DISPOSITIF DE CHAUFFAGE À HAUTE FRÉQUENCE

Publication
EP 3481150 A4 20190717 (EN)

Application
EP 17819947 A 20170620

Priority
• JP 2016129562 A 20160630
• JP 2016129564 A 20160630
• JP 2017022618 W 20170620

Abstract (en)
[origin: EP3481150A1] High-frequency heating device (100) includes first surface wave excitation body (103a), second surface wave excitation body (103b), first high-frequency power supply unit (110a), second high-frequency power supply unit (110b), and high-frequency power generation unit (120). First and second surface wave excitation bodies (103a) and (103b) are disposed at locations opposite to each other such that heating-target object (102) is put between the surface wave excitation bodies. This configuration provides high-frequency heating device (100) capable of heating and browning two faces of heating-target object (102) without using a heater or other heating sources.

IPC 8 full level
H05B 6/74 (2006.01); **H05B 6/70** (2006.01)

CPC (source: EP)
H05B 6/707 (2013.01); **H05B 2206/044** (2013.01)

Citation (search report)
• [X] JP H06260276 A 19940916 - MATSUSHITA ELECTRIC IND CO LTD
• [X] JP 2000150136 A 20000530 - NEC CORP
• [E] EP 3435738 A1 20190130 - PANASONIC IP MAN CO LTD [JP]
• [A] EP 1619933 A1 20060125 - MATSUSHITA ELECTRIC IND CO LTD [JP]
• See references of WO 2018003588A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 3481150 A1 20190508; EP 3481150 A4 20190717; EP 3481150 B1 20220223; CN 109315028 A 20190205; CN 109315028 B 20210702; EP 3661326 A1 20200603; EP 3661326 B1 20220420; WO 2018003588 A1 20180104

DOCDB simple family (application)
EP 17819947 A 20170620; CN 201780035498 A 20170620; EP 20152193 A 20170620; JP 2017022618 W 20170620